

BRA7N65
Rev. A Jul.-2023

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@ f Parameter	... Z Symbol	f › Rating	% y Unit
Drain-Source Voltage	V_{DSS}	650	V
Drain Current	$I_D(T_C=25^\circ\text{C})$	7.0	A
Drain Current	$I_D(T_C=100^\circ\text{C})$	4.4	A
Drain Current - Pulsed	I_{DM}	28	A
Gate-Source Voltage	V_{GS}	± 30	V
Single Pulsed Avalanche Energy	E_{AS}	420	mJ
Repetitive Avalanche Energy	E_{AR}	14.7	mJ
Avalanche Current	I_{AR}	7.0	A
Power Dissipation	$P_D(T_C=25^\circ\text{C})$	147	W

Operating and Storage Temperature Range

T_J, T_{STJ} 383.88 512.3 .48001 18.48 rc47998 18.48 re f BT 10.49584041139-55 to 13

BRA7N65

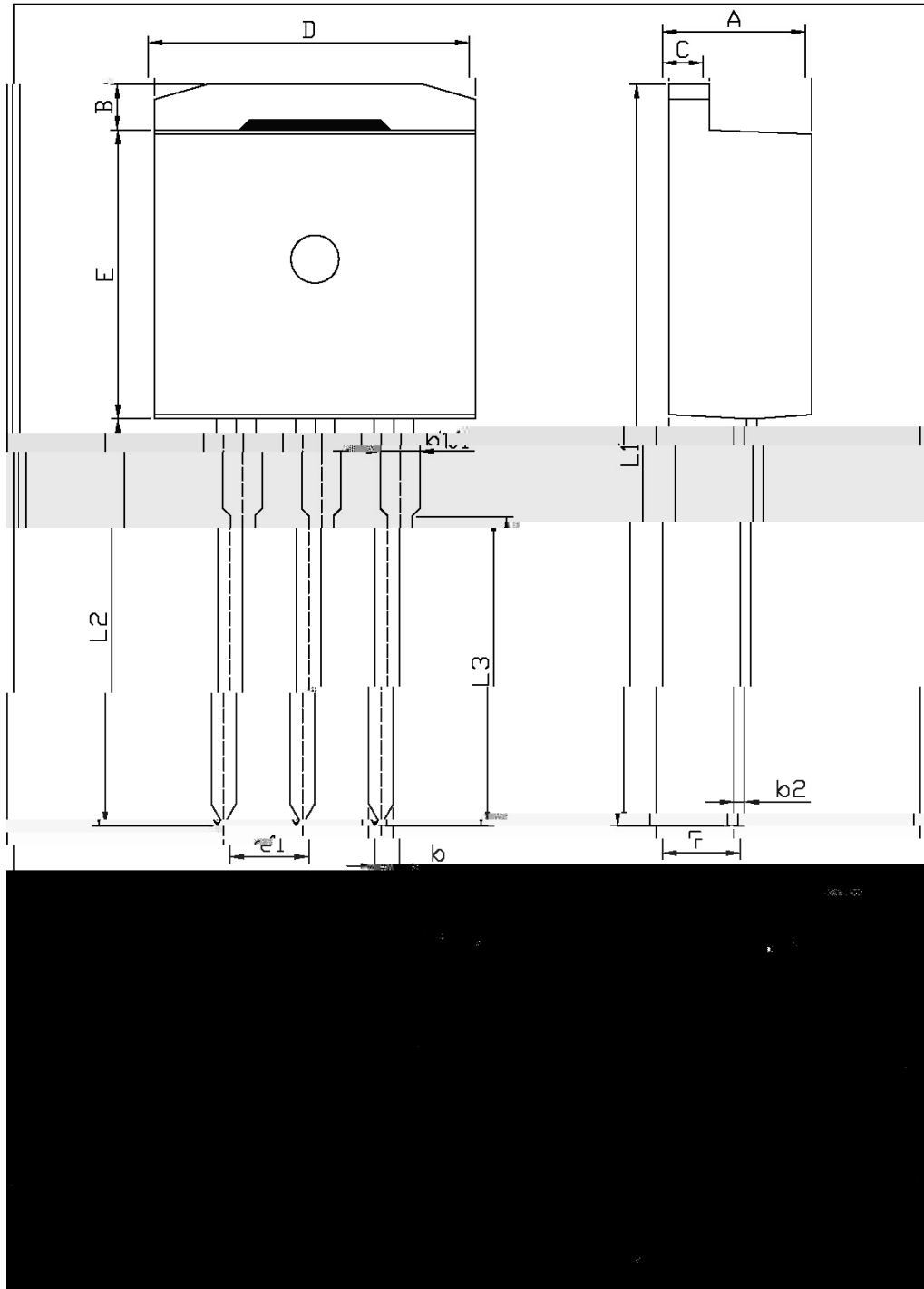
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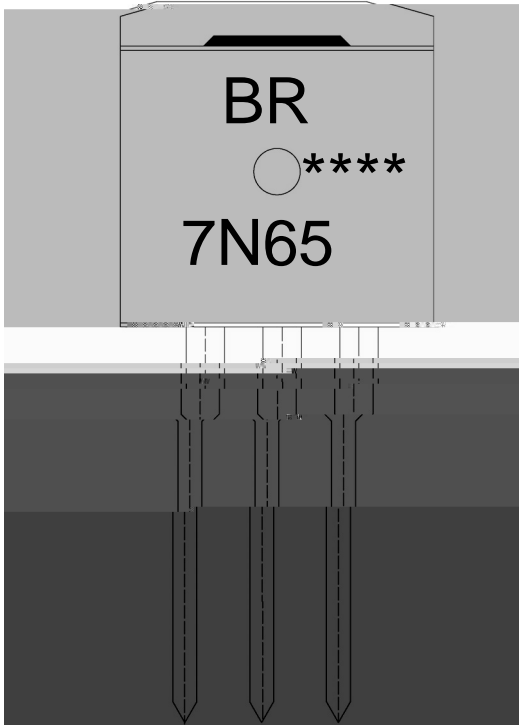


DATA SHEET

∅ □ =) φ / Package Dimensions

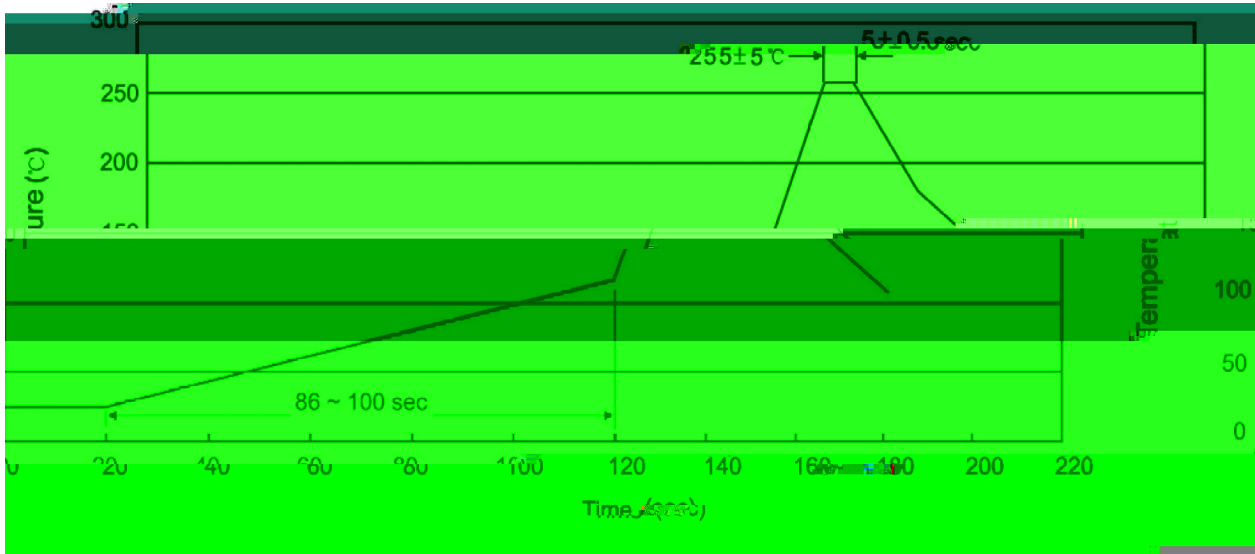


, M y f / Marking Instructions



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 Note:
 BR: Company Code
 7N65: Product Type
 ****: Lot No. Code, code change with Lot No

G PD t... • Ž Ć (x /) / Temperature Profile for Dip Soldering(Pb-Free)



1. Preheating:

25 ~ 150 °C, Time: 60 ~ 90 sec;

2. Peak Temp.: 255 ± 5 °C, Duration: 5 ± 0.5 sec;

3. Cooling Speed: 2 ~ 10 °C / sec.

Note:

1. Preheating: 25 ~ 150 °C, Time: 60 ~ 90 sec.

2. Peak Temp.: 255 ± 5 °C, Duration: 5 ± 0.5 sec.

3. Cooling Speed: 2 ~ 10 °C / sec.

Resistance to Soldering Heat Test Conditions

Temp.: 270 ± 5 °C

Time: 10 ± 1 sec

Temp.: 270 ± 5 °C

Time: 10 ± 1 sec

Packaging SPEC.

TUBE

Package Type	Units					Dimension (unit mm)		
	Units/Tube	Tubes/Inner Box	Units/Inner Box	Inner Boxes/Outer Boxes	Units/Outer Box	Tube	Inner Box	Outer Box
TO-262	50	20	1,000	5	5,000	532x31.4x5.5	555x164x50	575x290x180

Notices